Investigation on Discoloration on TO package





Objective of Investigation

- Discoloration on terminal and leadframe of TO packages are always reported at customer side.
- The discoloration is an optical effect of oxidized metal, it's seldom found at Infineon factory. It was considered a result of the humidity and thermal introduced during the transportation and storage.
- > To evaluate the impact of terminal and leadframe discoloration, we selected typical TO package products to evaluate it's FFFQR (form, fit, function, quality or reliability). Please refer to the details in below pages.

1. See if some discoloration level can still be use - I



 Similar case previously investigated that discolorations of the main terminals do not influence the electrical or solderability behavior.

> Results:

 Tested 60pcs, the results are all pass. That's to say the electrical function is ok.

(infineon

Solderability test results pass.





Solderability test

- > Sample size:2pcs
- > Precondition: 8 hours steam aging.
- Solderability test condition:

| 产品类型 | 无铂电镀产品 |
|---|---------------------------|
| Device Type | Lead-free plating devices |
| 协焊剂类型 | R0L1/R=100 |
| lux Type b焊剂浸入时间 lux Dipping Time | 5~10s |
| 早料类型 iolder Type | SnAgCu |
| 學料温度 Solder Temperature | 245±5℃ |
| 使入焊料时间 ime Dipping into older | 5±0.5s |
| B入/拿出焊料速度 peed Dipping nto/Taking out of older | 25±6mm/s |



before

The solder coverage of heatsink is >95% So the solderability test result is ok.



after 判定标准 Determinant Criteria 締約春区婚的焊料覆盖率在95%以上

Conversió El Infraste Tactivologias AG 2028, Albrichia rasano

Copyright © Infineon Tech

Solder coverage shall be above 95% on inspection area.

1. See if some discoloration level can still be use - II



- Thermal characterization of the Thermal Resistance (R_{th}) for 11 pcs of IDW10G120C5B complained devices.
- Results: All are still within datasheet specification

Rth Thermal Characterization

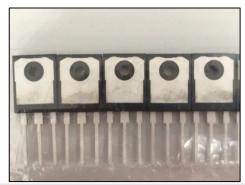
| Sample | Rth-JC/K/W per leg |
|-----------|-----------------------|
| 1 | 1.80 |
| 2 | 1.76 |
| 3 | 1.75 |
| 4 | 1.85 |
| 5 | 1.80 |
| 6 | 1.86 |
| 7 | 1.83 |
| 8 | 1.81 |
| 9 | 1.82 |
| 10 | 1.81 |
| 11 | 1.84 |
| average | 1.81 |
| Std. dev. | 0.03 |
| | 1.8% |

| Sample | Rth-JC/K/W per device |
|-----------|-----------------------|
| 1 | 0.90 |
| 2 | 0.91 |
| 3 | 0.94 |
| 4 | 0.93 |
| 5 | 0.92 |
| 6 | 0.95 |
| 7 | 0.89 |
| 8 | 0.91 |
| 9 | 0.92 |
| 10 | 0.93 |
| 11 | 0.91 |
| average | 0.92 |
| Std. dev. | 0.02 |
| | 1.9% |

IDW10G120C5B Thermal Resistances datasheet specification

| Thermal Resistances | | | | | | |
|--|----------------------|------------|--------------------|----------------|--------------|---------|
| Parameter Symb | Symbol | Conditions | Value (leg/device) | | | Unit |
| | Symbol | Conditions | min. | min. typ. max. | | 7 5/111 |
| Characteristic | | | | | | |
| Diode thermal resistance, junction – case | R _{th(j-c)} | | - | 1.6/0.8 | 2.0/1.0 | K/W |
| Thermal resistance, junction – ambient | R _{th(j-a)} | leaded | - | - | 62 | K/W |
| Final Data Sheet | | 4 | | Rev | ı. 2.0, 2014 | -06-10 |

IDW10G120C5B Complained Devices





1. See if some discoloration level can still be use - III



- Same thermal characterization of the Thermal Resistance (R_{th}) done for IKW40N120H3 and IDW40E65D1 complained devices.
- Results: All are still within datasheet specification

IKW40N120H3 Rth Thermal Characterization

| Sample | Rth-JC/K/W IGBT |
|-----------|---------------------------|
| IGBT S1 | 0.23 |
| IGBT S2 | 0.22 |
| IGBT S3 | 0.20 |
| IGBT S4 | 0.21 |
| IGBT S5 | 0.21 |
| IGBT S6 | 0.22 |
| average | 0.22 |
| Std. dev. | 0.01 |
| | 4.4% |

IDW40E65D1 Rth Thermal Characterization

| Sample | Rth-JC/K/W Diode |
|-----------|----------------------------|
| S1 | 0.54 |
| S2 | 0.50 |
| S3 | 0.49 |
| S5 | 0.50 |
| S8 | 0.52 |
| S10 | 0.53 |
| average | 0.51 |
| Std. dev. | 0.02 |
| | 3.5% |

IKW40N120H3 Rth datasheet spec

| Thermal Resistance | | | | |
|---|----------------------|------------|-------------|---------|
| Parameter | Symbol | Conditions | Max. Value | Unit |
| Characteristic | · | | · | |
| IGBT thermal resistance, junction - case | R _{th(j-c)} | | 0.31 | K/W |
| Diode thermal resistance, junction - case | R _{th(j-c)} | | 1.11 | K/W |
| Thermal resistance junction - ambient | R _{th(j-a)} | | 40 | K/W |
| | | • | Day 2.1 201 | 4 44 0/ |

Rev. 2.1, 2014-11-26

IDW40E65D1 Rth datasheet spec

| Thermal Resistance | | | | |
|--|----------------------|------------|--------------|---------|
| Parameter | Symbol | Conditions | Max. Value | Unit |
| Characteristic | | | | |
| Diode thermal resistance, 1) junction - case | R _{th(j-c)} | | 0.84 | K/W |
| Thermal resistance junction - ambient | $R_{th(j-a)}$ | | 40 | K/W |
| | • | | Pev 2.2 2013 | 2 12 16 |

Rev. 2.2, 2013-12-16



Summary

- The oxidation/discoloration located at the terminal and lead frame is only an optical effect, and there is no influence on FFFQR (form, fit, function, quality or reliability). There is no harmful integrations with the mechanical, and electrical surrounding to be expected. The phenomenon can be regarded as an optical effect.
- There is no negative impact on functionality and product quality.
- No change of electrical, thermal or mechanical parameters of the product will be caused by the above discoloration. The lifetime and reliability of the product will not be reduced by the discoloration mentioned above.



Part of your life. Part of tomorrow.

